

HSU285

Silicon Schottky Barrier Diode for High frequency detection

REJ03G0009-0100Z

Rev.1.00

Apr.16.2003

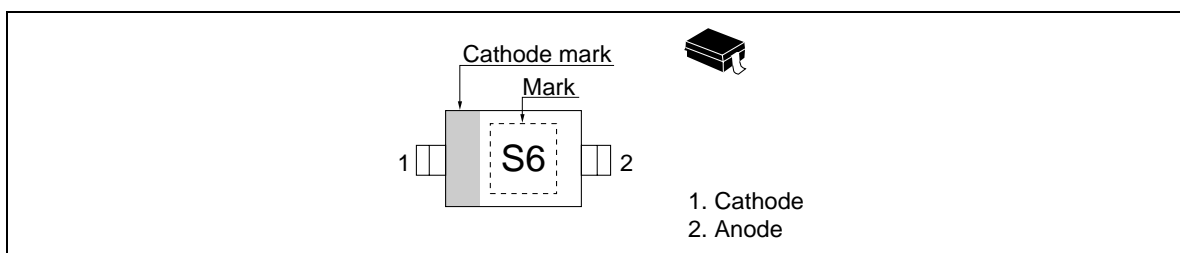
Features

- Low forward voltage, Low capacitance and High detection sensitivity.
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HSU285	S6	URP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	2	V
Average rectified current	I_O	5	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.15	V	$I_F = 0.1 \text{ mA}$
	V_{F2}	—	—	0.27		$I_F = 1 \text{ mA}$
Capacitance	C	—	0.3	—	pF	$V_R = 1 \text{ V}$, $f = 1 \text{ MHz}$
ESD-Capability *1	—	10	—	—	V	C = 200 pF, $R_L = 0 \Omega$, Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion ; $I_R > 100 \mu\text{A}$ at $V_R = 0.5 \text{ V}$

Main Characteristic

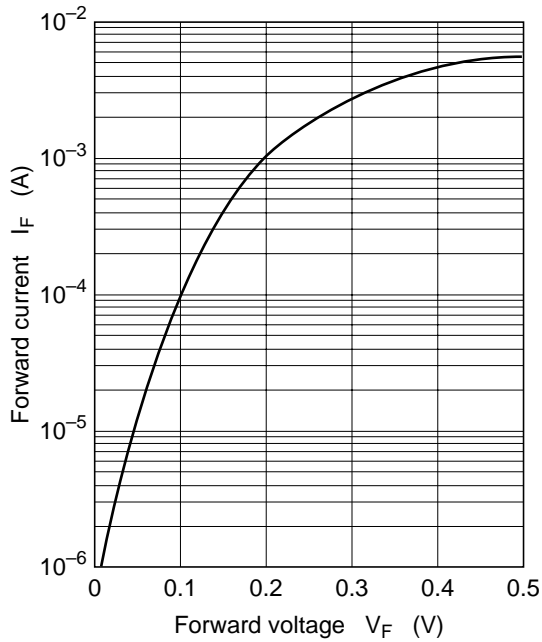


Fig.1 Forward current vs. Forward voltage

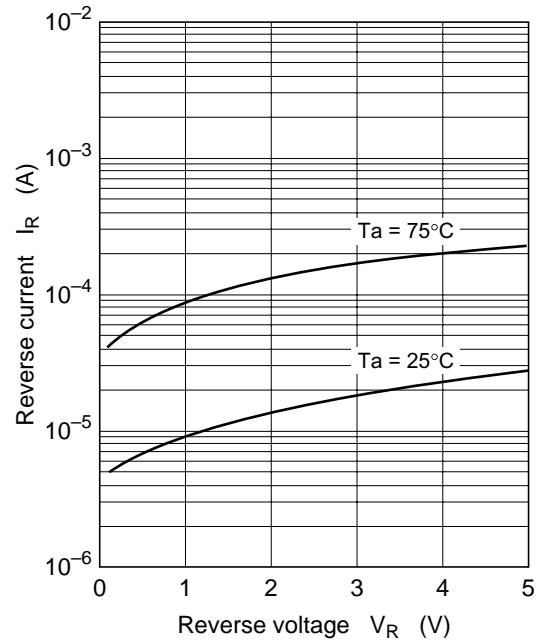


Fig.2 Reverse current vs. Reverse voltage

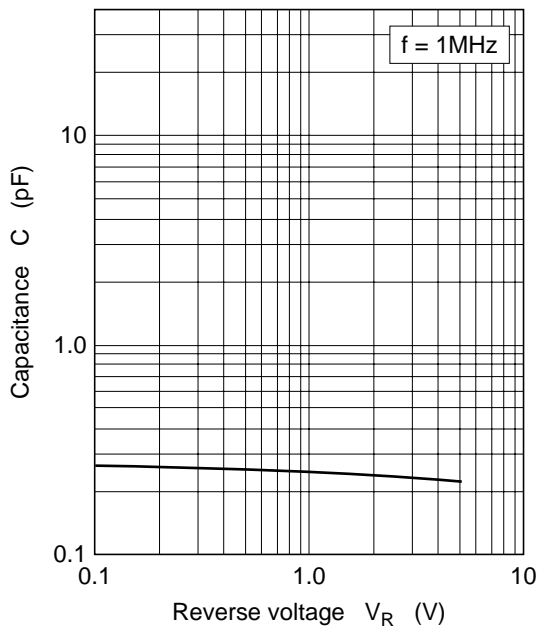
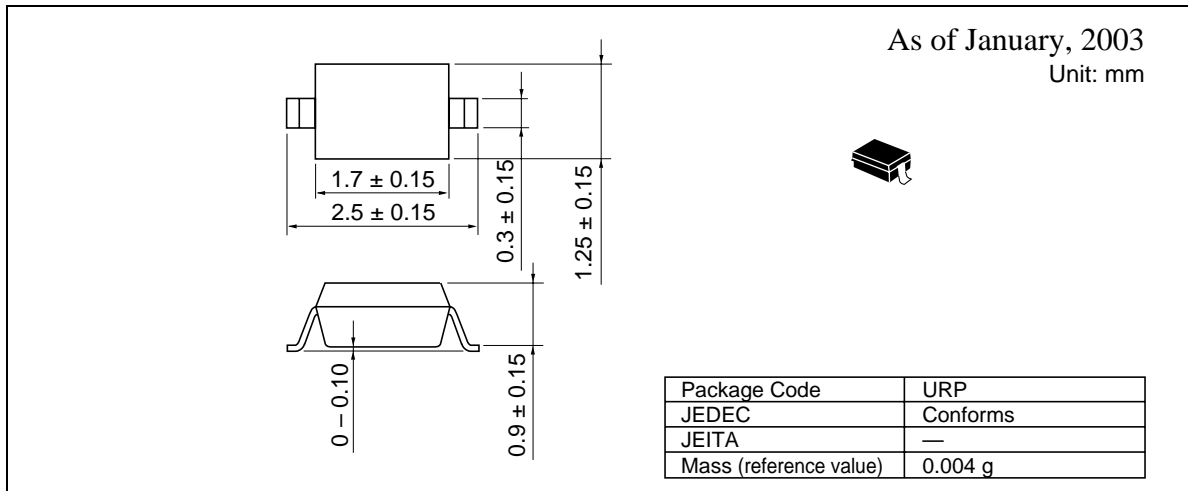


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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